01 / INDIVIDUAL PROFILE INFILL

Composite-floor 502

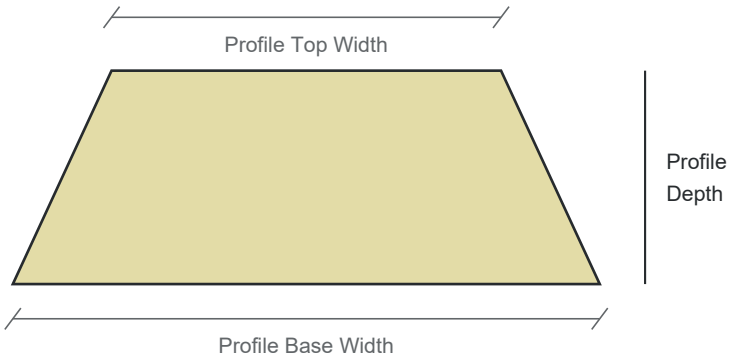
Ryan Bat 502 - Composite Flooring.rfa | Generic Model | Three embedded types; no TXT catalogue.

Use one independently placed trapezoidal infill for each recess that needs filling. The family represents the infill envelope. It does not need a steel deck or floor host, and does not distribute itself to deck ribs.

Type	Base width	Top width	Depth
ComFlor 60 - simplified trapezoid	180	120	60
ComFlor 80 - simplified trapezoid	180	120	80
Custom - editable trapezoid	200	100	50

All dimensions in mm. **Infill Length** starts at 500 mm and is an instance input. Duplicate a type before changing **Profile Base Width**, **Profile Top Width** or **Profile Depth**. Board Material is a type input.

SECTION ACROSS ONE INFILL / NTS



Profile depth is not stock-board thickness

RF_Board Thickness = 50 mm describes the stock product. Profile Depth is the overall recess envelope. A 60 or 80 mm envelope does not mean that one 50 mm sheet fills it, or calculate an approved layer count or purchased sheets.

The ComFlor 60/80 types are simplified trapezoidal starter profiles. Small stiffeners, steel thickness, embossments, re-entrant features and rounded corners are omitted.

02 / PLACE IN THE FLOOR RECESS

Position each infill

Level-based horizontal-floor workflow. Set each piece from the actual project geometry.

1 **Load and place**

Load the RFA. Use Component placement on the required level. No work plane or deck host is needed for normal placement.

2 **Set the lower datum**

Set Elevation from Level to the lower soffit datum where the flat base is required. Profile Depth rises from that base.

3 **Align with the recess**

Rotate in plan so the length follows the recess. Local X is across the section; local Y is along the recess; local Z is depth.

4 **Set Infill Length**

Length grows equally in both directions from the instance centre. Check each end against the actual opening and selected detail.

5 **Copy at the actual recesses**

Place or copy one piece per recess. There is no automatic deck detection, rib pitch or repeat array. Check every section and end position.

Coordinate the complete composite-floor detail

Ryanfire **V23.23 revision 2.0** shows 502 cut to the profile and extending 100 mm either side of the cored aperture. A 500 mm starter length does not enforce this for every opening. Use the complete current drawing for applicability, service, collar, sealing and fixings.

Placement limits

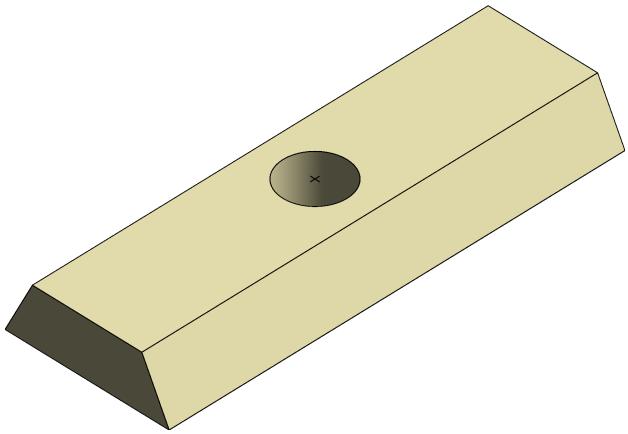
This configuration supports plan rotation for horizontal floor use. Arbitrary out-of-plane inclination is not supported. Starter profiles are simplified envelopes; fit them to the actual deck and coordinate the actual cut pieces and layers separately.

System reference: ryanfire.co.nz/systems/v23.23. The product family does not assign a fire rating. Enter the assessed system and revision per instance.

03 / OPENINGS AND SCHEDULES

Cut, join and quantify

The family is a solid infill envelope. Service openings require a suitable cutting family or project opening workflow.



Service opening through the composite infill. Verify the opening dimensions and position against the actual project service.

Create and verify the opening

Use the project's opening or void-cut workflow to create the required service opening in the infill. Make the cut pass through the full infill and align it with the actual service. Check the result in 3D and section.

Joining pieces

Use Revit Join Geometry for overlapping infill pieces where required. Joined pieces remain separate instances: joining does not merge their schedule counts or their identities.

Schedule field	Use
Count / Family / Type	Count placed infill instances. RF_Service Qty is not an infill count.
RF_Board Width / RF_Board Length	Shared instance outputs: maximum profile width and Infill Length.
RF_Board Thickness / Arrangement	Shared type outputs: 50 mm stock thickness and infill description.
RF_Penetration ID / Substrate / System Ref / System Revision / Fire Rating	Editable shared instance data for project identification and assessed system.